

Semiconductor devices — Mechanical and climatic test methods —

Part 11: Rapid change of temperature — Two-fluid-bath method

The European Standard EN 60749-11:2002 has the status of a
British Standard

ICS 31.080.01

National foreword

This British Standard is the official English language version of EN 60749-11:2002. It is identical with IEC 60749-11:2002, including Corrigendum 1:2003 and Corrigendum 2:2003. It partially supersedes BS EN 60749:1999.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors, which has the responsibility to:

- aid enquirers to understand the text;
- present to the responsible international/European committee any enquiries on the interpretation, or proposals for change, and keep the UK interests informed;
- monitor related international and European developments and promulgate them in the UK.

A list of organizations represented on this committee can be obtained on request to its secretary.

Cross-references

The British Standards which implement international or European publications referred to in this document may be found in the *BSI Catalogue* under the section entitled “International Standards Correspondence Index”, or by using the “Search” facility of the *BSI Electronic Catalogue* or of British Standards Online.

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This British Standard, having been prepared under the direction of the Electrotechnical Sector Policy and Strategy Committee, was published under the authority of the Standards Policy and Strategy Committee on 24 September 2002

Summary of pages

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Amendments issued since publication

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